Overview

HP ProBook 635 Aero G8 Notebook PC



- 1. Ambient Light Sensor (Optional)
- 2. Internal Microphones (2)
- 3. Webcam LED (Optional)
- 4. Camera Shutter (Only available with webcam)
- 5. HD and IR Camera (Optional)

Left

- 6. IR Camera LED (Optional)
- 7. Glass Clickpad
- 8. Audio Combo Jack
- 9. SuperSpeed USB Type-A 5Gbps signaling rate Port
- 10. SuperSpeed USB Type-A 5Gbps signaling rate Charging Port
- 11 Nano Security Lock Slot (Lock sold separately)



Overview



Right

- 1. Power Button Key
- 2. Power Connector
- 3. HDMI Port (Cable not included)
- SuperSpeed USB Type-C[®] 10Gbps signaling rate (Power delivery, DisplayPort[™] 1.4)
- 5. Nano SIM Card Slot¹
- 6. Touch Fingerprint Sensor (Select models)
- 1. All units have a SIM card tray but units that do not support WWAN are shipped with a non-removable SIM slot plug

QuickSpecs

Overview

At a Glance

- An ultralight sub-1 Kg laptop¹
- Choice of AMD Ryzen™ 5000 Series Mobile Processors.
- Enables AMD Memory Guard to help defend against cold boot attacks with real-time encryption and decryption of system's memory with AMD Ryzen PRO Processors.
- Preinstalled with Windows 10 versions or FreeDOS
- Choice of 13.3" (33.8 cm) diagonal ultra-wide viewing angle FHD and privacy panel option
- Supports wireless options for connectivity on the go including gigabit-speed Wi-Fi® 6 and CAT9 4G/LTE WWAN
- Fast and upgradeable dual channel DDR4 SODIMM memory up to 32 GB
- Choice of solid state drives up to 1 TB
- Features quiet and responsive HP Premium Keyboard with the HP Programmable key and backlit options
- Multi-layered security with HP Sure Start Gen7, HP Privacy Camera, HP Sure View Reflect, HP Sure Recover, HP Sure Run, HP Sure Sense, HP Sure Click, and Touch Fingerprint sensor
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles
- Battery life up to 15 hours and 30 minutes (42Whr) and up to 20 hours (53 Whr) (AMD Ryzen[™] 5000 Series Mobile Processors and 3-cell 53 Wh battery)
- Designed to support optional HP docking options including the HP Universal Dock G5 (Docks sold separately)
- Undergoes MIL-STD 810H tests ²
- 1. 250 nit panel, HP Sure View Reflect, multiple SODIMMs, WWAN, 53 Wh battery, and backlit keyboard not available on configurations starting at less than 1kg.
- MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP ProBook 635 Aero G8 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 64 – HP recommends Windows 10 Pro¹ Windows 10 Pro 64 (National Academic only)² Windows 10 Home 64¹ Windows 10 Home Single Language 64¹ Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)¹ Windows 10 Enterprise 64¹ (Web support)

FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information. Note: HP tested Windows 10, 20H2, 2004(20H1), 1909(19H2) on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282.

Supported Versions

HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

PROCESSORS

AMD Ryzen[™] 7 PRO 5850U with Radeon[™] Graphics (3.2 GHz base clock, up to 4.4 GHz max boost clock, 16 MB L3 cache, 8 cores) ^{3,4,5}

AMD Ryzen[™] 5 PRO 5650U with Radeon[™] Graphics (2.3 GHz base clock, up to 4.2 GHz max boost clock, 16 MB L3 cache, 6 cores)^{3,4,5}

AMD Ryzen[™] 7 5800U with Radeon[™] Graphics (1.9 GHz base clock, up to 4.4 GHz max boost clock, 16 MB L3 cache, 8 cores)^{3,4,5}

AMD Ryzen[™] 5 5600U with Radeon[™] Graphics (2.3 GHz base clock, up to 4.2 GHz max boost clock, 16 MB L3 cache, 6 cores) ^{3,4,5}

AMD Ryzen[™] 3 5400U with Radeon[™] Graphics (2.6 GHz base clock, up to 4.0 GHz max boost clock, 8 MB L3 cache, 4 cores) ^{3,4,5}

Processors Family

AMD Ryzen[™] 5000 Series Mobile Processors⁶

3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.



4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.

5. AMD Max Burst frequency performance varies depending on hardware, software and overall system configuration.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated AMD Radeon™ Graphics⁷

Supports

Support HD decode, DX12, HDMI2.0 7. FHD/HD content required to view FHD/HD images.

DISPLAY

Non-Touch

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare WLED-backlit bent, 250 nits, 45% NTSC (1920 x 1080) ^{7,9} 33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare WLED-backlit bent, 250 nits, 45% NTSC for HD camera (1920 x 1080) ^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare WLED-backlit bent, 250 nits, 45% NTSC for HD + IR camera (1920 x 1080) ^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP+PSR anti-glare, low power bent with Ambient Light Sensor, 400 nits, 100%sRGB for HD + IR camera (1920 x 1080)^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP+PSR anti-glare, low power bent with Ambient Light Sensor, 400 nits, 100%sRGB for HD + IR camera for WWAN (1920 x 1080)^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP + PSR anti-glare WLED-backlit bent, 1000 nits with HP Sure View Reflect Integrated Privacy Screen, 72% NTSC with Ambient Light Sensor and HD + IR camera (1920 x 1080)^{7,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP + PSR anti-glare WLED-backlit bent, 1000 nits with HP Sure View Reflect Integrated Privacy Screen, 72% NTSC with Ambient Light Sensor and HD + IR camera for WWAN (1920 x 1080) ^{7,9,10}

HDMI⁸

Support resolution up to 4k @ 60Hz

7. FHD/HD content required to view FHD/HD images.

- 8. HDMI cable sold separately.
- 9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.



10. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

NOTE: Actual brightness will be lower with touchscreen or Sure View.

STORAGE AND DRIVES

Primary M.2 Storage

1 TB PCIe[®] Gen3 x4 NVMe[™] TLC Solid State Drive¹¹ 512 GB PCIe[®] Gen3x4 NVMe[™] TLC Solid State Drive¹¹ 512 GB PCIe[®] NVMe[™] Value Solid State Drive¹¹ 256 GB PCIe[®] Gen3x4 NVMe[™] TLC Solid State Drive¹¹ 256 GB PCIe[®] NVMe[™] Value Solid State Drive¹¹ 128 GB M.2 PCIe TLC Solid State Drive¹¹

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows
 is reserved for system recovery software.

MEMORY

Maximum Storage 32 GB DDR4-3200 SDRAM

Memory

32 GB DDR4-3200 SDRAM (2 x 16 GB) ¹² 16 GB DDR4-3200 SDRAM (1 x 16 GB) ¹² 16 GB DDR4-3200 SDRAM (2 x 8 GB) ¹² 8 GB DDR4-3200 SDRAM (1 x 8 GB) ¹² 8 GB DDR4-3200 SDRAM (2 x 4 GB) ¹² 4 GB DDR4-3200 SDRAM (1 x 4 GB) ¹²

Memory Slots

2 SODIMM Both slots are accessible/upgradeable by IT or self-maintainers only DDR4 SODIMMS, system runs at 3200 Supports Dual Channel Memory

12. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



NETWORKING/COMMUNICATIONS

WLAN

Intel[®] AX200 Wi-Fi 6 (2x2) and Bluetooth[®] 5 Combo, non-vPro[®] ¹³ Realtek RTL8822CE 802.11ac (2x2) and Bluetooth[®] 5 Combo¹³

WWAN

Intel[®] XMM[™] 7360 LTE-Advanced Cat 9 ¹⁴

13. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

14. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

AUDIO/MULTIMEDIA

Audio

Integrated microphone (Dual Array) 2 Integrated Stereo Speakers

Speaker Power 2W/4ohm Per speaker

Camera 720p HD camera ^{7,43} 720p HD+IR camera ^{7,43,15}

Sensors Ambient light sensor (select models only) Hall Sensor

7. FHD/HD content required to view FHD/HD images.

43. Sold separately or as an optional feature.

15. Internet access required.



KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant, Durakeys Backlit keyboard¹⁶

Pointing Device

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching F2 - Blank or SureView On/Off (with LED) F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute (with LED) F6 - Volume Down F7 - Volume Up F8 - Mic Mute (with LED) F9 - Blank or Backlit Toggle F10 - Insert F11 - Airplane Mode F12 - HP Programmable Key Print Screen Power Button (with LED)

Hiden Function Keys

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock Fn+E - Insert Fn+W - Pause

16. Backlit keyboard is an optional feature.



SOFTWARE AND SECURITY

HP BIOSphere Gen6¹⁷ HP Drive Lock & Automatic Drive Lock BIOS Update via Network HP Secure Erase¹⁸ Absolute Persistence Module¹⁹ HP LAN-Wireless Protection USB enable/disable (via BIOS)

Software

HP Connection Optimizer ²⁰ HP Hotkey Support myHP HP Support Assistant ²¹ HP Noise Cancellation Software Touchpoint Customizer for Commercial HP QuickDrop²² HP Notifications HP Privacy Settings HP Wireless Button Driver HP Power Manager Microsoft Defender Buy Office (sold separately) HP Smart Support ⁴⁶

Manageability Features

HP Driver Packs (download) ²³ HP Manageability Integration Kit for Microsoft Center Configuration manager Gen4 (download) ²⁴ HP Client Catalog (download) HP Client Management Script Library (download) HP Image Assistant (download)

Security Management

HP Wolf Pro Security Edition ²⁵ HP Sure Click ²⁶ HP Sure Sense ²⁷ HP Sure Start Gen7 ²⁸ HP Sure Admin ²⁹ HP Sure Recover Gen4 ³⁰ HP Sure Run Gen4 ³¹ HP Fingerprint Sensor ³² TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified) Secured-core PC Enable³³

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

UEFI version: 2.7 Class: Class 3

17. HP BIOSphere Gen6 requires Windows 10 and is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.



18. HP Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

19. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/ 20. HP Connection Optimizer requires Windows 10.

21. HP Support Assistant requires Windows and Internet access.

22. HP Quick Drop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

23. HP Driver Packs not preinstalled, however available for download at

http://www.hp.com/go/clientmanagement.

24. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

25. HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.

26. HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A_SureClick for complete details

27. HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.

28. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10

29. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

30. HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.

31. HP Sure Run Gen4 is available on select HP PCs and requires Windows 10

32. HP Fingerprint sensor is an optional feature that must be configured at purchase.

33. Secured-core PC Enable Requires an Intel[®] vPro[®], AMD Ryzen[™] Pro processor or Qualcomm[®] processor with SD850 or higher and requires 8 GB or more system memory. Secured-core PC functionality can be enabled from the factory.

46. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

POWER



Power Supply

HP Smart 65 W External AC power adapter ³⁴ HP Smart 65 W EM External AC power adapter ³⁴ HP Smart 65 W USB Type-C adapter ³⁴ HP Smart 45 W External AC power adapter ³⁴ HP Smart 45 W External AC power adapter, 2-prong (Japan only) ³⁴ HP Smart 45 W USB Type-C adapter ³⁴

Power Cord 3-wire plug – 1.0m ³⁴

 $2-\text{wire plug} - 1.0\text{m}^{34}$

Primary Battery

HP Long Life 3-cell, 42 Wh Li-ion ^{35,44} HP Long Life 3-cell, 53 Wh Li-ion ^{35,44} Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter) ³⁶

Battery life

MM18 Battery life 42 Wh battery: Up to 15 hours 30 minutes⁴⁵ 53 Wh battery: Up to 20 hours⁴⁵

Battery Weight

42W battery: 0.17 kg (0.37 lb) 53W battery: 0.21 kg (0.45 lb)

34. Availability may vary by country.

35. Battery is internal and not replaceable by customer. Serviceable by warranty.

36. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

44. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

45. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.



WEIGHTS & DIMENSIONS

Product Weight Starting at 2.2 lb ³⁷ Starting at 0.99 kg ³⁷

Product Dimensions (w x d x h) 400 nits panels: 30.76 x 20.45 x 1.79 cm 12.11 x 8.05 x 0.71 in

1000 nits panels: 30.76 x 20.45 x 1.79 cm 12.11 x 8.05 x 0.71 in

250 nits panels: 30.76 x 20.45 x 1.92 cm 12.11 x 8.05 x 0.756 in

37. Weight will vary by configuration.

PORTS/SLOTS

Ports

SuperSpeed USB Type-C[®] 10Gbps signaling rate (Power delivery, DisplayPort[™] 1.4)
 SuperSpeed USB Type-A 5Gbps signaling rate (1 charging port)
 HDMI 2.0 ³⁸
 Headphone/microphone combo
 AC power
 Nano SIM card slot ³⁹

38. HDMI cable sold separately.39. SIM slot is not user accessible without WWAN configuration.



SERVICE AND SUPPORT

1-year and 3-year limited warranties and 90-day software limited warranty options depending on country. Batteries have a default one-year limited warranty except for HP Long Life batteries which will follow the one- or threeyear warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁴⁰

40. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)		
Nominal Operating Voltage	19 V	
Average Operating Power	2.82W	
Integrated graphics	6.78W	
Discrete Graphics	N/A	
Max Operating Power	UMA < 45W	
Temperature		
Operating	41° to 95° F (5° to 35° C)	
Non-operating	-4° to 140° F (-20° to 60° C)	
Relative Humidity		
Operating	10% to 90%, non-condensing	
	_	
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature	
Shock		
Operating	40 G, 2 ms, half-sine	
Non-operating	200 G, 2 ms, half-sine	
Random Vibration		
Operating	0.75 grms	
Non-operating	1.50 grms	
Altitude (unpressurized)		
Operating	-50 to 10,000 ft (-15.24 to 3,048 m)	
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)	
Planned Industry Standard Certifications		
UL	Yes	
CSA	Yes	
FCC Compliance	Yes	
ENERGY STAR [®]	ENERGY STAR 8.0 ⁴¹	
EPEAT [®]	EPEAT [®] Gold in United States ⁴²	
ICES	Yes	
Australia /	Yes	
NZ A – Tick Compliance	Yes	
CCC	Yes	
Japan VCCI Compliance	Yes	
KC	Yes	
BSMI	Yes	
CE Marketing Compliance	Yes	
BNCI or BELUS CIT	Yes Yes	
GOST	Yes	
Saudi Arabian Compliance (ICCP)	Yes	
SABS	Yes	
41. Configurations of the HP ProBook 635 Aero G8 that are ENERGY STAR [®] qualified are identified as ProBook 635 Aero G8		
ENERGY STAR on HP websites and on http://www.energystar.gov.		
42 Based on LIS EPEAT® registration according to IEEE 1680 1-2018 EPEAT® EPEAT® status varies by country. Visit		

42. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] status varies by country. Visit http://www.epeat.net for more information.



DISPLAYS

NOTE: All specifications represent the typical specifications provided by hp's component manufacturers; actual performance may vary either higher or lower.

1.Actual brightness will be lower with touchscreen or Sure View.

Panel LCD 13.3 inch FHD (1920 x 1080) Anti-Glare	Outline Dimensions (W x H x D)	300.56 x 177.77 mm (max) (FPC folding included)
	Active Area	293.76 x 165.24 mm
WLED UWVA 45percent cg 250nits eDP 1.2 w/o PSR	Weight	260 g (max)
bent NWBZ	Diagonal Size	13.3 inch
	Thickness	3.0 mm/ 5.0 mm (PCB) (max)
	Interface	eDP 1.2 (2lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	600:1
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	RGB Stripe
	Backlight	LED
	Color Gamut Coverage	NTSC 45%
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85

Panel LCD 13.3 inch FHD (1920x1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NB2Y

Outline Dimensions (W x H x D)	299.06 x 176.54 mm (max) (FPC folding included)
Active Area	293.76 x 165.24 mm
Weight	175 g (max)
Diagonal Size	13.3 inch
Thickness	2.0 mm / 3.8 mm (PCB) (max)
Interface	eDP 1.4 w/ PSRII (2 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1500:1
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB Stripe
Backlight	LED
Color Gamut Coverage	sRGB 100%
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85



Panel LCD 13.3inch FHD
(1920x1080) Anti-Glare
WLED UWVA 72percent cg
1000nits eDP 1.4+PSR
PrivacyG4

299.06 x 176.54 mm (max)
293.76 x 165.24 mm
220 g (max)
13.3 inch
3.9 mm (max)
eDP 1.4 + PSR (4 lane)
Anti-glare (AG)
No
1500:1
60 Hz
1000 nits
1920 x 1080 (FHD)
RGB
LED
NTSC 72%
8 bits
UWVA 85/85/85/85

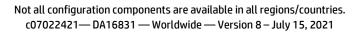


STORAGE AND DRIVES¹

1 For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 128GB 2280 PCle-3x2 Three Layer Cell	Form Factor	M.2 2280
	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCle NVMe Gen3x2 or Gen 3x4
	Maximum Sequential Read	Up to 3100 MB/s
	Maximum Sequential Write	Up to 1400 MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (Option); TRIM; L1.2
SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell	Form Factor Capacity	M.2 2280 1 TB
	Form Factor	M.2 2280
single-sided		
	NAND Type	TLC 0.09 in (2.3 mm)
	Height Width	
	Weight	0.87 in (22 mm)
	Interface	0.02 lb (10 g)
		PCIe NVMe Gen3X4
	Maximum Sequential Read	Up to 3500 MB/s
	Maximum Sequential Write	Up to 3037 MB/s
	Logical Blocks	2,000,409,264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2

CameCapacity256 GBNAND TypeValueHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3Maximum Sequential ReadUp to 2200 MB/sMaximum Sequential WriteUp to 1400 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 512GB 2280 PCIe NVMeForm FactorMAND TypeValueHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3MAND TypeValueHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential ReadUp to 2400 MB/sMaximum Sequential ReadUp to 1750 MB/sLogical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe-Form FactorM.2 2280	SSD 256GB 2280 PCIe NVMe	Form Factor	M.2 2280
Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NWMe Gen3Maximum Sequential ReadUp to 2200 M8/sMaximum Sequential WriteUp to 1400 M8/sLogical Blocks500,118,192Operating Temperature32' to 159'F (0' to 70'C) [ambient temp]FeaturesAt Security (optional); TRIM; L1.2SSD 512GB 2280 PCIe NVMeForm FactorKalueM.2 2280Capacity512 GBNAND TypeValueHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Width0.82 lb (10 g)InterfacePCle NVMe Gen3Maximum Sequential WriteUp to 1750 M8/sLogical Blocks1,000,215,215Operating Temperature32' to 158'F (0' to 70'C) [ambient temp]FeaturesAt Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIEForm FactorSSD 45 CGB 2280 M2 PCIEForm FactorSSD 45 CGB 2280 M2 PCIEForm FactorMaximum Sequential WriteUp to 1750 M8/sLogical Blocks1,000,215,215Operating Temperature32' to 158'F (0' to 70'C) [ambient temp]FactorM.2 2280Capacity256 GBMAND TypeTLCHeight0.99 in (2.3 mm)Width0.97 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 M8/sMaximum Sequential ReadUp to 3500 M8/sMaximum	Value	Capacity	256 GB
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SSD 256GB 2280 M2 PCIe Form Factor M2 200 MB/s Maximum Sequential Write Up to 2200 MB/s Maximum Sequential Write Up to 1400 MB/s Logical Blocks 500,118,192 Operating Temperature 32* to 158* f(0* to 70*C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 512CB 2280 PCIe NVMe Form Factor M.2 2280 Capacity 512 GB Value Capacity 512 CB MAXimum Sequential Write 0.09 in (2.3 mm) Width 0.67 in (22 mm) Width 0.67 in (22 mm) Width 0.67 in (22 mm) Weight 0.02 ib (10 g) Interface PCle NVMe Gen3 Maximum Sequential Read Up to 2400 MB/s Maximum Sequential Write Up to 750 MB/s Logical Blocks 1,000,215,215 Operating Temperature 32* to 158* F (0* to 70*C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 256GB 2280 M2 PCie Form Factor M.2 2280 Capacity 256 GB Capacity 256 GB NAND Type TL Height<		Height	0.09 in (2.3 mm)
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Maximum Sequential Read Up to 2200 MB/s Maximum Sequential Write Up to 1400 MB/s Logical Blocks 500,118,192 Operating Temperature 32*to 158*F (0° to 70°C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 51268 2280 PCIe NVMe Form Factor M.2 2280 Capacity 512 GB NAND Type Value Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3 Maximum Sequential Read Up to 2400 MB/s Logical Blocks 1,000,215,215 Operating Temperature 32*to 158*F (0° to 70°C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 25568 2280 M2 PCIe- Form Factor M.2 2280 Capacity 256 GB Capacity SSD 25568 2280 M2 PCie- Form Factor M.2 2280 Capacity 256 GB Capacity ATA Security (optional); TRIM; L1.2 Capacity 256 GB SSD 25568 2280 M2 PCie- Form Factor M.2 2280 Capacity 256 GB <th></th> <th>Weight</th> <th>0.02 lb (10 g)</th>		Weight	0.02 lb (10 g)
Maximum Sequential Write Up to 1400 MB/s Logical Blocks 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 512GB 2280 PCIe NVMe Form Factor Capacity S12 GB NAND Type Value Height 0.05 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3 Maximum Sequential Read Up to 2400 MB/s Logical Blocks 1,000,215,215 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features SSD 256GB 2280 M2 PCIe Form Factor Capacity SSD 256GB 2280 M2 PCIe Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.82 in 158°F (0° to 70°C) [ambient temp] Features SSD 256GB 2280 M2 PCIe Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3 Maximum Sequential Read Up to 3500 MB/s Maximum Sequential Read Up to 2200 MB/s Maximum Sequential Read Up to 3200 MB/s Maximum Sequential Read Up to 2200 MB/s Logical Blocks 0.09 in (2.3 mm) Width 0.87 in (22 mm) Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Height 0.91 in (2.3 mm) Width 0.87 in (22 mm) Height 0.91 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.92 in (2.3 mm) Width 0.93 in (2.3 mm) Width 0.95 in (2.3		Interface	PCIe NVMe Gen3
Logical Blocks500, 118, 192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 51268 2280 PCIe NVMeForm FactorM.2 2280Capacity512 GBNAND TypeValueHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3Maximum Sequential ReadUp to 2400 MB/sLogical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 2566B 2280 M2 PCIe- 3x4 SS NVMe TLCForm FactorMAND TypeLCHeight0.09 in (2.3 mm)With0.87 in (22 mm)Muximum Sequential WriteUp to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe- 3x4 SS NVMe TLCForm FactorMAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Muth0.87 in (22 mm)Mitch0.87 in (22 mm)Mitch0.97 in (2.3 mm)Width0.87 in (22 mm)Maximum Sequential WriteUp to 3500 MB/sMaximum Sequen		Maximum Sequential Read	Up to 2200 MB/s
Operating Temperature 32* to 158*F (0* to 70*C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 5126B 2280 PCIe NVMe Form Factor M.2 2280 Capacity 512 GB NAND Type Value Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3 Maximum Sequential Read Up to 2400 MB/s Maximum Sequential Write Up to 1750 MB/s Logical Blocks 1,000,215,215 Operating Temperature 32* to 158*F (0* to 70*C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 2556GB 2280 M2 PCIe- Form Factor M.2 2280 Capacity 256 GB NAND Type TLC Height 0.09 in (2.3 mm) Width 0.37 in (22 mm) Interface PCle NVMe Gen3X4 MAND Type TLC Height 0.91 in (2.3 mm) Width 0.37 in (22 mm) Interface PCle NVMe Gen3X4 Maximum Sequential Read Up to 2200 MB/s <t< th=""><th></th><th>Maximum Sequential Write</th><th>Up to 1400 MB/s</th></t<>		Maximum Sequential Write	Up to 1400 MB/s
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SSD 5126B 2280 PCIe NVMe Form Factor M.2 2280 Capacity 512 GB NAND Type Value Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3 Maximum Sequential Read Up to 2400 MB/s Maximum Sequential Write Up to 1750 MB/s Logical Blocks 1,000,215,215 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 236GB 2280 M2 PCie- Form Factor MAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface PCle NVMe Gen3X4 MAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface PCle NVMe Gen3X4 Maximum Sequential Read Up to 3500 MB/s Maximum Sequential Read Up to 2200 MB/s Logical Blocks 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]		Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Value Capacity 512 GB NAND Type Value Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCle NVMe Gen3 Maximum Sequential Read Up to 2400 MB/s Maximum Sequential Write Up to 1750 MB/s Logical Blocks 1,000,215,215 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 256GB 2280 M2 PCle- 3x4 SS NVMe TLC Form Factor Maximum Sequential Write Up to 1750 MB/s Logical Blocks 1,000,215,215 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security (optional); TRIM; L1.2 SSD 256GB 2280 M2 PCle Form Factor M.2 2280 Capacity 256 GB NAND Type Height 0.09 in (2.3 mm) With Width 0.87 in (22 mm) Maximum Sequential Read Width 0.87 in (22 mm) Maximum Sequential Read Width 0.87 in (22 mm) Maximum Sequential Write Up to 3500 MB/s		Features	ATA Security (optional); TRIM; L1.2
CambonCapacity512 GBNAND TypeValueHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential WriteUp to 1750 MB/sLogical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesXA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCle- 3x4 SS NVMe TLCForm FactorM.2 2280Capacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential WriteUp to 3500 MB/sLogical Blocks0,018/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]	SSD 512GB 2280 PCIe NVMe	Form Factor	M.2 2280
NAND TypeValueHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential WriteUp to 1750 MB/sLogical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCle-Form FactorMAND TypeLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMAND TypeUp to 3500 MB/sMAND Sequential ReadUp to 2200 MB/sLogical Blocks0,09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential ReadUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]	Value	Capacity	512 GB
Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential WriteUp to 1750 MB/sLogical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe- 3x4 SS NVMe TLCForm FactorMAND TypeM.2 2280Capacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		NAND Type	Value
Weight0.02 lb (10 g)InterfacePCle NVMe Gen3Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential WriteUp to 1750 MB/sLogical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe- 3x4 SS NVMe TLCForm FactorMAND TypeLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential ReadUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Height	0.09 in (2.3 mm)
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Maximum Sequential WriteUp to 1750 MB/sLogical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe- Sax4 SS NVMe TLCForm FactorCapacity256 GBANND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Interface	PCIe NVMe Gen3
Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe- 3x4 SS NVMe TLCForm FactorM.2 2280Capacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Read	Up to 2400 MB/s
Operating Temperature Features32° to 158°F (0° to 70°C) [ambient temp] ATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe- Sx4 SS NVMe TLCForm FactorM.2 2280 CapacityCapacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Write	Up to 1750 MB/s
FeaturesATA Security (optional); TRIM; L1.2SSD 256GB 2280 M2 PCIe- 3x4 SS NVMe TLCForm FactorM.2 2280Capacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Logical Blocks	1,000,215,215
SSD 256GB 2280 M2 PCle- 3x4 SS NVMe TLCForm FactorM.2 2280Capacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
3x4 SS NVMe TLCCapacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Features	ATA Security (optional); TRIM; L1.2
Capacity256 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]	SSD 256GB 2280 M2 PCIe-	Form Factor	M.2 2280
Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]	3x4 SS NVMe TLC	Capacity	256 GB
Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		NAND Type	TLC
InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Height	0.09 in (2.3 mm)
Maximum Sequential ReadUp to 3500 MB/sMaximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Width	0.87 in (22 mm)
Maximum Sequential WriteUp to 2200 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Interface	PCIe NVMe Gen3X4
Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Read	Up to 3500 MB/s
Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Write	Up to 2200 MB/s
		Logical Blocks	500,118,192
Features ATA Security; TRIM; L1.2		Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
		Features	ATA Security; TRIM; L1.2



SSD 512GB 2280 M2 PC	le-
3x4 SS NVMe TLC	

Form Factor	M.2 2280
Capacity	512 GB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Weight	0.02 lb (10 g)
Interface	PCIe NVMe Gen3X4
Maximum Sequential Read	Up to 3500 MB/s
Maximum Sequential Write	Up to 2956 MB/s
Logical Blocks	1,000,215,215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2



NETWORKING / COMMUNICATIONS

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Intel® Wi-Fi 6 ¹ AX200 + Bluetooth® 5 (802.11ax 2x2, non-vPro®, supporting gigabit data rate) non-vPro® ⁵	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11ac IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Features Wi-Fi 6 technology
	Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b : +17dBm minimum 802.11g : +16dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum



QuickSpecs

Technical Specifications

	 802.11n HT20(5GHz): 802.11n HT40(5GHz): 802.11ac VHT80(5GHz) 802.11ac VHT160(5GHz) 802.11ax HE40(2.4GHz) 802.11ax HE80(5GHz) 802.11ax HE160(5GHz) 	+13dBm minimum) : +10dBm minimum z) : +10dBm minimum z) : +12dBm minimum : +10dBm minimum
Power Consumption	 Transmit mode: 2.0 W Receive mode:1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW 	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity ⁴	 802.11ac, MCS0(VHT80) : -84dBm maximum 802.11ac, MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT160) : -58.5dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE80): -54dBm maximum 802.11ax, MCS11(HE160): -53.5dBm maximum 	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Туре 2230: 2.8 g 2. Туре 126: 1.3 g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED Off – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

4	ש

Signaling Data Rate	Legacy: 3 Mbps signaling data rate ⁶ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 6. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.

 Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. Only available in countries where 802.11ax is supported.
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



Realtek RTL8822CE 802.11ac 2x2 Wi-Fi + Bluetooth5 ¹	Wireless LAN Standards	IEEE 802.11a
		IEEE 802.11b
		IEEE 802.11g IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi [®] CERTIFIED modules
	Frequency Band	• 802.11b/g/n
		2.402 – 2.482 GHz
		• 802.11a/n/ac
		4.9 – 4.95 GHz (Japan)
		5.15 – 5.25 GHz
		5.25 – 5.35 GHz 5.47 – 5.725 GHz
		5.825 – 5.850 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	Data Nates	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11n: max 300Mbps
		• 802.11ac : max 866.7Mbps
	Modulation	Direct Sequence Spread Spectrum
		BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only
		AES-CCMP: 128 bit in hardware
		802.1x authentication
		• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
		WPA2 certification
		WPA3 certification IEEE 802.11i
		• WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	• 802.11b: +18.5dBm minimum
	• -	• 802.11g: +17.5dBm minimum
		• 802.11a: +18.5dBm minimum
		• 802.11n HT20(2.4GHz): +15.5dBm minimum
		• 802.11n HT40(2.4GHz): +14.5dBm minimum
		• 802.11n HT20(5GHz): +15.5dBm minimum
		• 802.11n HT40(5GHz): +14.5dBm minimum
		• 802.11ac VHT80(5GHz): +11.5dBm minimum



Power Consumption	 Transmit mode: 2.0 W Receive mode: 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW 		
Power Management	ACPI and PCI Express cor 802.11 compliant power	npliant power management saving mode	
Receiver Sensitivity ⁴	 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF LED Off – Radio ON		

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)



Signaling Data Rate	Legacy: 3 Mbps signaling data rate ⁵ throughput up to2.17 Mbps BLE: 1 Mbps signaling data rate ¹ throughput up to 0.2 Mbps 5. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intel® XMM™ 7360 LTE- Advanced¹	Technology/Operating bands	FDD LTE: LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12), 700 (Band 13) 700 (Band 17), 850 (Band 18), 850 (Band 19), 800 (Band 20), 1450 (Band 21), 850 (Band 26) 700 (Band 28) MHz, 700 (Band 29), 2300 (Band 30), 2100 (Band 66) MHz TDD LTE: 2600 (Band 38), 1900 (Band 39), 2300 (Band 40), 2500 (Band 41) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-B and LTO)
	GPS bands	GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 ± 2.046 MHz
	Maximum data rates	LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	М.2, 3042-S3 Кеу В
	Weight	6 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

1. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.



POWER

AC Adapter 45 Watt Smart	Dimensions	95 x 45 x 26.8 mm	
nPFC Standard Barrel 4.5mm Right Angle 1m	Weight	200 g +/- 10 g	
	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standard SELV; Agency approvals - (FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.

AC Adapter 45 Watt Smart	Dimensions	95 x 45 x 26.8 mm	
nPFC Standard Barrel 4.5mm Right Angle 1m	Weight	200 g +/- 10 g	
2prong	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar SELV; Agency approvals – FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.

AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1m	: Dimensions (H x W x D) Weight Input	90 x 51 x 28.5mm 230g +/-10% Input Efficiency Input frequency range Input AC current	88.0 % at 115 Vac and 89.0 % at 230 Vac 47 ~ 63 Hz Max. 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE. 5 at 25°C ambient condition.

AC Adapter 65 Watt Smart nPFC EM Barrel 4.5mm New EM	t Dimensions (H x W x D)	102 x 55 x 30mm	
	Weight	250g +/-10%	
NEW EM	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Certifications	SELV; Agency approvals - FCC Class B, CISPR22 Class	ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE. rs at 25°C ambient condition.
AC Adapter 45 Watt nPFC	Dimensions (H x W x D)	94.0 x 40.0 x 26.5 mm	
Standard USB Type-C® Straight 1m	Weight	192.5g +/-10%	
Straight fin	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power DC output Hold-up time	5V/15W 9V/27W 12V/36W 15V/45W 5V/9V/12V/15V 5 ms at 115 Vac input



	Connector	USB Type-C®	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		-	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standard SELV; Agency approvals - (FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.
AC Adapter 65 Watt nPFC	Dimensions	90.0 x 51 x 28.5mm	
Standard USB type C® Straight 1m	Weight	250 g +/- 10 g	
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.6 A at 90 VAC and maximum load
	Output	Output power	65 W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	8.0A Max.
	Connector	USB Type C [®]	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standard SELV; Agency approvals - (FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.



	Dimensions (H x W x L)	7.3 x 52.9 x 267.11mm (0.287 x 2.082 x 10.516 inch)
Long Life -PL Fast Charge	Weight	0.205kg (0.45 lb)
	Cells/Type	3cell Lithium-Ion Polymer cell / 645180
	Voltage	11.55V
	Amp-hour capacity	4.59Ah
	Watt-hour capacity	53 Wh
	Temperature	32° to 113° F (0° to 45° C)
	Operating (Charging)	32° to 122° F (0° to 50° C)
	Operating (Discharging)	14° to 140° F (-10° to 60° C)
	Warranty	Depends on system offering
	Optional Travel Battery Available	Νο

Battery GR 3 Cell 42 Wh Long Life -PL Fast Charge	Dimensions (H x W x L) Weight	5.8 x 61.5 x274.4 mm (0.228 x 2.42 x 10.80 inch) 0.168 kg (0.37 lb)
	Cells/Type	3cell Lithium-Ion Polymer cell / 485083
	Energy	
	Voltage	11.4V
	Amp-hour capacity	3.64Ah
	Watt-hour capacity	42 Wh
	Temperature	
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 122° F (-10° to 60° C) Warranty: Depends on system offering
	Fuel Gauge LED	NA



ENVIRONMENTAL DATA

ENVIRUNMENTAL DA		or is in the process of heirs a	wtified to the following approvale and may be	
& declarations	-		ertified to the following approvals and may be	
a ucciai aliviis	labeled with one or more o			
	IT ECO declaration			
	US ENERGY STAR	8		
	US Federal Energy	y Management Program (FEM	Р)	
	 EPEAT^D Gold regis 	stered in the United States. Se	e http://www.epeat.net for registration	
	status in your cou	intry.		
	 TC0 8.0 			
	China Energy Con	servation Program (CECP)		
		onmental Protection Administ	ration (SEPA)	
	Taiwan Green Ma			
	Korea Eco-label			
	Japan PC Green la	hel*		
	Jupante dicenta			
Sustainable Impact	Ocean-bound plastic in (part(s))		
Specifications	• 14.12% post-consumer r			
•	External Power Supply 9	5		
	Low halogen	0% Efficiency		
	-	ted cushions are 100% sustai	nably coursed and regulable	
	_			
		on inside box is 100% sustain	ably sourced and recyclable	
	Bulk packaging available			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the			
	Notebook model is based (on a "Typically Configured No	tebook".	
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Sort	5.66 W	5.41 W	5.68 W	
idle)	5.00 W	5.41 W	5.00 W	
•	0.02.111	1.20.11	1.02.14	
Normal Operation (Long	0.93 W	1.28 W	1.02 W	
idle)	0.02.111	4.20.11	4.02.14	
Sleep	0.93 W	1.28 W	1.02 W	
Off	0.36 W	0.38 W	0.36 W	
	family. HP computers mar Environmental Protection family does not offer ENER	ked with the ENERGY STAR [®] L Agency (EPA) ENERGY STAR [®] RGY STAR [®] compliant configu PC featuring a hard disk drive,	mpliant product if offered within the model ogo are compliant with the applicable U.S. specifications for computers. If a model rations, then energy efficiency data listed is a high efficiency power supply, and a	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	19 BTU/hr	18 BTU/hr	19 BTU/hr	
Normal Operation (Long	3 BTU/hr	4 BTU/hr	3 BTU/hr	
idle)				



Sleep	3 BT	U/hr	4 BTU/hr		3 BTU/hr	
Off	1 BTU/hr 1 BTU		1 BTU/hr		1 BTU/hr	
	*NOTE: Heat attained for	•	calculated based on t	he measured watts, ass	suming the service level is	
Declared Noise		Sound Power		Sound	Pressure	
Emissions		(L _{WAd} , bels)		(L _{pAm} , c	lecibels)	
(in accordance with ISO 7779 and ISO 9296)						
Typically Configured – Idle		2.5			14.4	
Fixed Disk – Random writes		2.6		1	6.9	
Optical Drive – Sequential reads		3.3		2	5.8	
Longevity and Upgrading	 This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. 			ral years. Upgradeable		
				to "5" years after the end of		
	 This (WE This Drin This http Plas ISO 	EE) Directive – s product is in c king Water and product is in c ://www.epeat stics parts weig 1043.	2002/96/EC. compliance with Calif d Toxic Enforcement compliance with the I .net ghing over 25 grams	ornia Proposition 65 (St Act of 1986). EEE 1680 (EPEAT) stanc	lard at the Gold level, see marked per ISO11469 and	
Packaging Materials	External:	PAPER/Corrugated			261 g	
	Internal:	PLASTIC/polypropylene		3 g		
		PLASTIC/Polyethylene low density		14 g		
	PAPER/Molded pulp 170 g					
	The plastic packaging material contains at least 0% recycled content.					
	The corrugated paper packaging materials contains at least 54.5% recycled content.					
RoHS Compliance	restrictions i products wo legislation in	n the Europear rldwide throug Europe, as we	n Union (EU) Restricti Ih the HP GSE. HP has Ill as China, India, and	on of Hazardous Substa contributed to the deve Vietnam.		
	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.					



	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS
	requirements for virtually all relevant products by July 2013, and we will continue to extend the
	scope of the commitment to include further restricted substances as regulations continue to evolve.
	To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to
	the HP General Specification for the Environment at
	http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
	Asbestos
	Certain Azo Colorants
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
	• Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	Bis(2-Ethylhexyl) phthalate (DEHP)
	Benzyl butyl phthalate (BBP)
	• Dibutyl phthalate (DBP)
	Diisobutyl phthalate (DIBP)
	• Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	 Nickel – finishes must not be used on the external surface designed to be frequently
	handled or carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	• Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in
	packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.



End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly			
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.			
HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:			
Information	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html			
	Eco-label certifications			
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html			
	ISO 14001 certificates:			
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and			
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf			
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials. 			

FINGERPRINT READER

Model	Synaptics Validity VFS7604 touch sensor
Mobile Voltage Operation	3.0V to 3.6V
Operating Temperature:	0~60°C
Current Consumption Image:	100mA Max
Low Latency Wait For Finger	260 uA
Capture Rate: Image transmitter output frequency	9.6MHz
ESD Resistance	IEC 61000-4-2 4B (+/-15KV)
Detection Matrix	363 dpi / 7.4x6mm sensor area
FRR (False Reject Rate) / FAR (False Acceptance Rate)	FRR <1% @ 1:50K FAR



Country of Origin

China



QuickSpecs

Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Prelude Pro Top Load	1X645AA
	HP Prelude Pro Backpack	1X644AA
		ТЛОТТАА
Docking	HP USB-C Mini Dock	1PM64AA
	HP USB-C Travel Dock G2	7PJ38AA
Input/Output	HP WL USB Agnes Keyboard	T6U20AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Wireless USB Premium Keyboard	Z9N41AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
	HP 235 WL Mouse and Keyboard Combo	1Y4D0AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wired Desktop 320K Keyboard	9SR37AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP 125 Wired Keyboard	266C9AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP Wired Mouse	265A9AA
	HP LSR Wired Mouse	265D9AA
	HP Bluetooth Travel Bluetooth Mouse	6SP30AA
	HP Comfort Grip USB Wireless Mouse	H2L63UT
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1D0K8AA
	HP USB Travel USB Mouse	G1K28AA
	HP USB-A+Bluetooth Multi-Device 635 Wireless Mouse Black	1D0K2AA
	HP X4000b Bluetooth Mouse	НЗТ5ОАА
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP USB Fingerprint Mouse	4TS44AA
	HP Elite Presenter Mouse	2CE30AA
	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to VGA Adapter	N9K76AA
	HP USB to Gig RJ45 Adapter	NJR76AA N7P47AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA



QuickSpecs

Options and Accessories (sold separately and availability may vary by country)

	HP 65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP 45W USB-C LC Dali AC Power Adapter	1MZ01AA
	HP USB-C Essential Power Bank	3TB55AA
Storage	HP External USB Optical Drive	F2B56AA
Memory	HP 4GB DDR4 3200 Memory	286H5AA
i iciiioi y	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA
Convitu		CU11/4744
Security	HP Sure Key Cable Lock	6UW42AA
	HP Nano Keyed Cable Lock	1AJ39AA



Summary of Changes

Date of change:	Version History:		Description of change:	
April 20, 2021	V1 to V2	Updated	Memory Section and Input/ Output Section Updated	
April 26, 2021	V2 to V3	Updated	BIOS information in Software section/Environmental Data	
May 6, 2021	V3 to V4	Added	HP Smart Support	
May 11, 2021	V4 to V5	Updated	Product Dimensions	
May 27, 2021	V5 to V6	Update	HP Pro Security Edition to HP Wolf Pro Security Edition	
June 11, 2021	V6 to V7	Removed	ed HP WorkWell from Software and Security Section	
July 15, 2021	V7 to V8	Update	Storage and Drives section, At a Glance and Networking section	

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